



Material Content Data Sheet



Sales Product Name		TLE7244SL		Issued		24. January 2018		
MA#		MA001687814						
Package		PG-SSOP-24-7		Weight*		147.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.128	3.49	3.49	34854	34854
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8464	
wire	non noble metal	copper	7440-50-8	50.568	34.37	35.27	343683	352676
	noble metal	gold	7440-57-5	0.765	0.52	0.52	5196	5196
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1160
plastics		epoxy resin	-	7.854	5.34		53380	
	inorganic material	silicondioxide	60676-86-0	77.347	52.55	58.01	525681	580221
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11417	11417
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2482	2482
glue	plastics	acrylic resin	-	0.426	0.29		2894	
	noble metal	silver	7440-22-4	1.510	1.03	1.32	10260	13154
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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